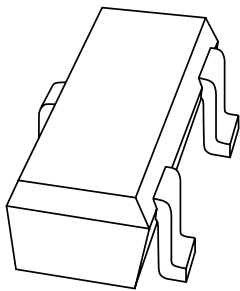


# DATA SHEET



**2PB709A**

**PNP general purpose transistor**

Product data sheet  
Supersedes data of 1997 Jun 19

1999 Apr 23

## PNP general purpose transistor

## 2PB709A

## FEATURES

- Low current (max. 100 mA)
- Low voltage (max. 45 V).

## APPLICATIONS

- General purpose switching and amplification.

## DESCRIPTION

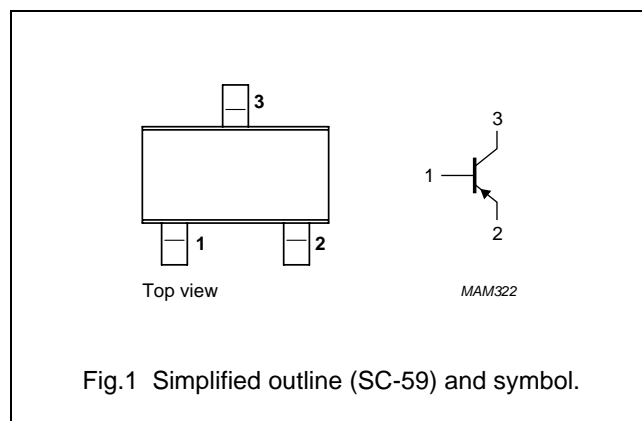
PNP transistor in an SC-59 plastic package.  
NPN complement: 2PB601A.

## MARKING

TYPE NUMBER	MARKING CODE
2PB709AQ	BQ
2PB709AR	BR
2PB709AS	BS

## PINNING

PIN	DESCRIPTION
1	base
2	emitter
3	collector



## LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{CBO}$	collector-base voltage	open emitter	—	–45	V
$V_{CEO}$	collector-emitter voltage	open base	—	–45	V
$V_{EBO}$	emitter-base voltage	open collector	—	–6	V
$I_C$	collector current (DC)		—	–100	mA
$I_{CM}$	peak collector current		—	–200	mA
$I_{BM}$	peak base current		—	–100	mA
$P_{tot}$	total power dissipation	$T_{amb} \leq 25\text{ °C}$ ; note 1	—	250	mW
$T_{stg}$	storage temperature		–65	+150	°C
$T_j$	junction temperature		—	150	°C
$T_{amb}$	operating ambient temperature		–65	+150	°C

## Note

1. Transistor mounted on an FR4 printed-circuit board.

## PNP general purpose transistor

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## THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j-a}$	thermal resistance from junction to ambient	note 1	500	K/W

## Note

1. Transistor mounted on an FR4 printed-circuit board.

## CHARACTERISTICS

$T_{amb} = 25\text{ }^{\circ}\text{C}$  unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$I_{CBO}$	collector cut-off current	$I_E = 0; V_{CB} = -45\text{ V}$	—	–10	nA
		$I_E = 0; V_{CB} = -45\text{ V}; T_j = 150\text{ }^{\circ}\text{C}$	—	–5	$\mu\text{A}$
$I_{EBO}$	emitter cut-off current	$I_C = 0; V_{EB} = -5\text{ V}$	—	–10	nA
$h_{FE}$	DC current gain 2PB709AQ 2PB709AR 2PB709AS	$I_C = -2\text{ mA}; V_{CE} = -10\text{ V}$	160	260	
			210	340	
			290	460	
$V_{CEsat}$	collector-emitter saturation voltage	$I_C = -100\text{ mA}; I_B = -10\text{ mA}; \text{note 1}$	—	–500	mV
$C_c$	collector capacitance	$I_E = I_E = 0; V_{CB} = -10\text{ V}; f = 1\text{ MHz}$	—	5	pF
$f_T$	transition frequency 2PB709AQ 2PB709AR 2PB709AS	$I_C = -1\text{ mA}; V_{CE} = -10\text{ V}; f = 100\text{ MHz}$	60	—	MHz
			70	—	MHz
			80	—	MHz

## Note

1. Pulse test:  $t_p \leq 300\text{ }\mu\text{s}$ ;  $\delta \leq 0.02$ .

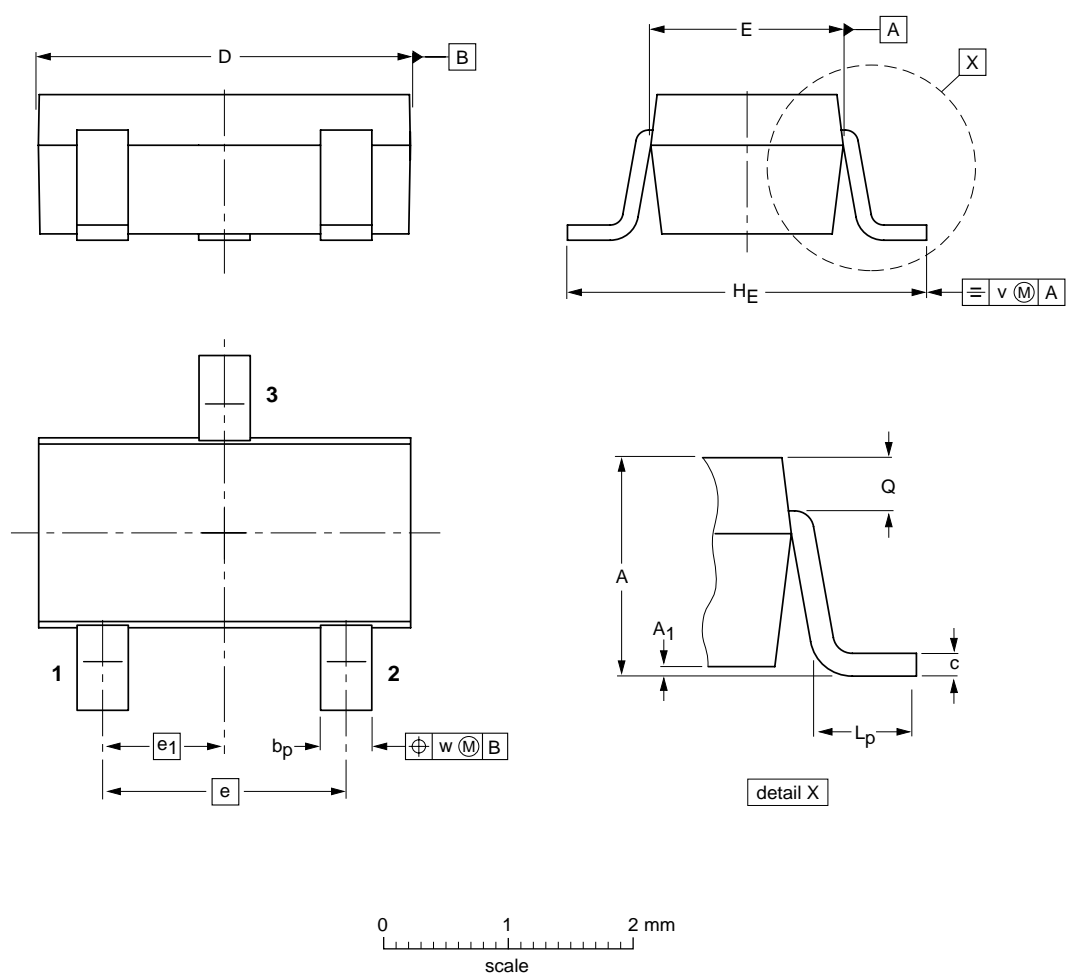
PNP general purpose transistor

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PACKAGE OUTLINE


Plastic surface mounted package; 3 leads

SOT346



DIMENSIONS (mm are the original dimensions)

UNIT	A	A <sub>1</sub>	b <sub>p</sub>	c	D	E	e	e <sub>1</sub>	H <sub>E</sub>	L <sub>p</sub>	Q	v	w
mm	1.3 1.0	0.1 0.013	0.50 0.35	0.26 0.10	3.1 2.7	1.7 1.3	1.9	0.95	3.0 2.5	0.6 0.2	0.33 0.23	0.2	0.2

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT346		TO-236	SC-59			98-07-17

## PNP general purpose transistor

2PB709A

## DATA SHEET STATUS

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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## **Customer notification**

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## **Contact information**

For additional information please visit: **<http://www.nxp.com>**

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